EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	2	"6970362".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/13 13:31
L2	2	"6104082".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/13 13:49
L3	9548	((flipchip (flip adj chip) microchip ((chip die dice ic (integrated adj circuit) microelectronic microprocessor element) with (microbump bump ball bga)))) same (interpos$4 capos$4 intermiedat$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/13 13:58
L4	7734	(packag$4 assembly structure) and 3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/13 13:59
L5	6658	(electrode land pad bondpad contact terminal) and 4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/13 14:08
L6	4693	5 and (substrate carrier board pcb motherboard)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/13 14:16
L7	3010	(epoxy fiberglass bypass capacitor asic (application adj specific)) and 6	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/13 14:18
L8	3005	(through via thru throughhole opening connection) and 7	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/13 14:24

| L9 | 2930 | (pattern$4 array plurality mulitple) and 8 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2007/09/13 14:25 |